PATENT ARSTRACTS OF JAPAN

(11) Publication number: 2001093940 A

(43) Date of publication of application: 06.04.01

(51) Int. CI H01L 21/60 C08G 59/40

H01L 21/56

(21) Application number: 11267008

(22) Date of filing: 21.09.99

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(54) METHOD FOR ASSEMBLING SEMICONDUCTOR DEVICE

(57) Abstract:

assembling a semiconductor device by which a elements with a substrate provided with electric manufacturing step can be shortened greatly and is winngs, heating/fluidizing the thermosetting liquid excellent in realiability.

SOLUTION: This method for assembling a liquid sealing resin composition contains an epoxy semiconductor device includes a step 1 for applying resin of two functions or more, a curing agent a thermosetting liquid sealing resin composition to having a flux work, and a curing promoter. a wafer wherein the number of semiconductor elements having solder bumps for electric

connection are formed, a step 2 for making the thermosetting liquid sealing resin composition to be tack-free, a step 3 for dicing the wafer into individual semiconductor elements, and a step 4 for PROBLEM TO BE SOLVED: To provide a method for electrically jointing the separated semiconductor sealing resin composition, and cooling it and press-fitting them. In this case, the thermosetting

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